



From layout to chips

2017 CMP Annual Users' Meeting

MPW Service Center for IC / MEMS Prototyping

<http://cmp.imag.fr>

Grenoble - France



Annual users' meeting introduction

- **Welcome to our 34th CMP annual users' meeting**
- This year, almost **all our partners are attending** the meeting which make this meeting unique in terms of possible interactions between CMP users' community and IC manufacturers and packaging houses.
- As usual, the meeting is dedicated to **updated data and information** on our services, **new offers and up coming services**.
- It is also a unique opportunity for you to **ask and feedback on our services**.
 - ➔ **Brief 2016 activity review**
 - ➔ **Annual meeting agenda**



Services and activities in 2016

- **Regular activity in 2016** with over 200 projects including about 45 small volume productions. **Activity in saw shape** for a few years. **Slight activity reduction (-10%)** since 2012.
- **Worldwide success with STM 28nm FDSOI** with over 50 projects last year and more than 145 since our first tape out. In 2016, over **95% CMP ams MPW** tapes out and above **75% CMP ST MPW** tapes out with respect to schedule.
 - MPW cancellations are mainly due to lack of participation.
 - At least 2 tapes out guaranteed per year for most advanced technologies.
- CMP MPW turnaround cycles analysis for each technologies. **ams turnaround times remain stable. ST technology turnaround times updated** based on last years experience:
 - From 28 to 38 weeks in 28nm
 - From 24 to 28 weeks in 55nm
 - From 20 to 26 weeks in 65nm



Services and activities in 2016

- **ams, Redtree and CMP team up** to bring further projects on CMP ams MPW. Operating as a **business developer**, Redtree helps CMP customers in their technology choice and supply chain.
- Ongoing developments of our **services in advanced packaging** with our **partners ams and CEA LETI**.
- **New services** : Photonics, Interposer, advanced packaging, wafer level post-processes.
- Ongoing **developments of our com, tools, tutorials, procedures...**
Yesterday took place our **first prototype initiation day**: 13 participants attended this session for beginners.



Annual meeting agenda

09:20- Introduction, *Jean-Christophe Crébier, CMP*

09:30- Statistics and evolution for 2016, *Kholdoun Torki, CMP*

09:45- STMicroelectronics MPW services, *Romain Verly, CMP*

10:05- 28nm FD-SOI RTL to GDS design flow tutorial, new developments,
Christelle Rabache, CMP

10:20- OxRAM memories: a disruptive technology for disruptive designs,
Luca Perniola, CEA LETI

10:40 *Break + Discussion*

11:10- ams MPW services, *Kholdoun Torki, CMP*

11:30- Hot Topics at ams in 2017, *Andreas Wild, ams*

11:50- Flip-chip & Advanced packaging, *Lyubomir Kerachev & Olivier Guiller, CMP*

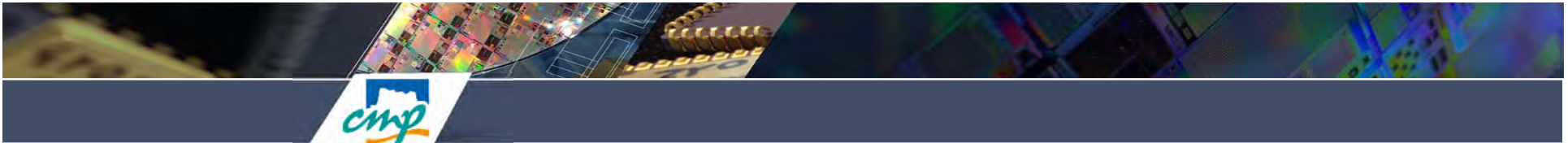
12:25- More than Moore MPW services, *Azedine Manaa, CMP*

12:40- Photonic IC design using PhoeniX Software solutions, *Luis Jorge, PhoeniX
Software*

13:00- Closing remarks, *Jean-Christophe Crébier, CMP*

13:10 *Lunch + Discussion*

14:00- End of CMP users annual meeting



Thank you !

